

TG-S606P Thermal Compound



Thermal Compound

TG-S606P is an ultra high performance silicone grease It has a thermal conductivity of 8 W/mK, superior wetting characteristics, resulting in a very low thermal resistance and excellent long term reliability.

Features

Good thermal conductivity Easy to assemble High stability Does not harden with time

Applications

Electronic components: IC, CPU, MOS LED, M/B, P/S, Heat Sink LCD TV, Notebook PC, PC Telecom Device, Wireless Hub, etc. DDR II Module, DVD Applications, Hand-set applications, etc.

Properties

🗸 REACH Compliant

ROHS Compliant

Property	TG-S606P	Unit	Test Method
Colour	White	-	Visual
Thermal Conductivity	8.0	W/mK	ASTM D5470
Weight Loss	<0.5	%	ASTM E595
Density	2.3	g/cm³	ASTM D792
Working Temperature	-40 to 180	°C	-
Volume Resistance	>1012	Ohm-cm	ASTM D257

Standard Packaging

Size	Packaging	Weight (gr)	
	Plastic Jar	300ml	
	Pail	1 kg	

Storage

TG-S606P has a self-life of eighteen (18) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened contained at, or below 25° C.

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